MR754 and MR760 are Preferred Devices

# **High Current Lead Mounted Rectifiers**

## Features

- Current Capacity Comparable to Chassis Mounted Rectifiers
- Very High Surge Capacity
- Insulated Case
- Pb–Free Packages are Available\*

## **Mechanical Characteristics:**

- Case: Epoxy, Molded
- Weight: 2.5 grams (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Lead is Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Cathode Polarity Band



# **ON Semiconductor®**

http://onsemi.com

HIGH CURRENT LEAD MOUNTED SILICON RECTIFIERS 50 – 1000 VOLTS DIFFUSED JUNCTION







## **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

**Preferred** devices are recommended choices for future use and best overall value.

\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## MAXIMUM RATINGS

Characteristic	Symbol	MR750	MR751	MR752	MR754	MR756	MR760	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	50	100	200	400	600	1000	V
Non-Repetitive Peak Reverse Voltage (Halfwave, single phase, 60 Hz peak)	V <sub>RSM</sub>	60	120	240	480	720	1200	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	35	70	140	280	420	700	V
Average Rectified Forward Current (Single phase, resistive load, 60 Hz) (See Figures 5 and 6)	Ι <sub>Ο</sub>	22 (T <sub>L</sub> = 60°C, 1/8 in Lead Lengths) 6.0 (T <sub>A</sub> = 60°C, P.C. Board mounting)			A			
Non–Repetitive Peak Surge Current (Surge applied at rated load conditions)	I <sub>FSM</sub>	400 (for 1 cycle)			A			
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +175			°C			

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

Characteristic and Conditions		Max	Unit
Maximum Instantaneous Forward Voltage Drop ( $i_F = 100 \text{ A}, T_J = 25^{\circ}\text{C}$ )		1.25	V
Maximum Forward Voltage Drop ( $I_F = 6.0 \text{ A}, T_A = 25^{\circ}\text{C}, 3/8 \text{ in leads}$ )		0.90	V
	۱ <sub>R</sub>	25 1.0	μA mA



Figure 4. Typical Transient Thermal Resistance









Figure 8. Steady State Thermal Resistance





Use of the above model permits junction to lead thermal resistance for any mounting configuration to be found. Lowest values occur when one side of the rectifier is brought as close as possible to the heat sink as shown below. Terms in the model signify:

 $T_A$  = Ambient Temperature  $T_C$  = Case Temperature

 $T_L$  = Lead Temperature  $T_J$  = Junction Temperature

 $\overline{R_{\theta S}}$  = Thermal Resistance, Heat Sink to Ambient

 $R_{\theta L}$  = Thermal Resistance, Lead to Heat Sink

 $R_{\theta J}$  = Thermal Resistance, Junction to Case

P<sub>F</sub> = Power Dissipation

(Subscripts A and K refer to anode and cathode sides, respectively.) Values for thermal resistance components are:

 $R_{\theta L}$  = 40°C/W/in. Typically and 44°C/W/in Maximum.

 $R_{\theta J} = 2^{\circ}C/W$  typically and  $4^{\circ}C/W$  Maximum.

Since  $R_{\theta,J}$  is so low, measurements of the case temperature,  $T_C$ , will be approximately equal to junction temperature in practical lead mounted applications. When used as a 60 Hz rectifierm the slow thermal response holds  $T_{J(PK)}$  close to  $T_{J(AVG)}$ . Therefore maximum lead temperature may be found from:  $T_L = 175^\circ$ - $R_{\theta,JL}$  PF. PF may be found from Figure 7. The recommended method of mounting to a P.C. board is shown on the

The recommended method of mounting to a P.C. board is shown on the sketch, where  $R_{\theta JA}$  is approximately 25°C/W for a 1–1/2" x 1–1/2" copper surface area. Values of 40°C/W are typical for mounting to terminal strips or P.C. boards where available surface area is small.





The rectification efficiency factor  $\sigma$  shown in Figure 9 was calculated using the formula:

$$\sigma = \frac{P_{(dc)}}{P_{(rms)}} = \frac{\frac{V_{20}(dc)}{R_{L}}}{\frac{V_{20}(rms)}{R_{L}}} \cdot 100\% = \frac{V_{20}(dc)}{V_{20}^{(ac)} + V_{20}^{(dc)}} \cdot 100\%$$
(1)

For a sine wave input  $V_m \sin (wt)$  to the diode, assumed lossless, the maximum theoretical efficiency factor becomes:

$$\sigma_{\text{(sine)}} = \frac{\frac{V^2 m}{\pi^2 R_L}}{\frac{V^2 m}{4 R_1}} \cdot 100\% = \frac{4}{\pi^2} \cdot 100\% = 40.6\%$$
(2)

. ....

$$\sigma_{\text{(square)}} = \frac{\frac{V^2 m}{2R_L}}{\frac{V^2 m}{R_L}} \cdot 100\% = 50\%$$
(3)

(A full wave circuit has twice these efficiencies)

As the frequency of the input signal is increased, the reverse recovery time of the diode (Figure 10) becomes significant, resulting in an increasing AC voltage component across RL which is opposite in polarity to the forward current, thereby reducing the value of the efficiency factor  $\sigma$ , as shown on Figure 9.

It should be emphasized that Figure 9 shows waveform efficiency only; it does not provide a measure of diode losses. Data was obtained by measuring the AC component of Vo with a true rms AC voltmeter and the DC component with a DC voltmeter. The data was used in Equation 1 to obtain points for Figure 9.

## **ORDERING INFORMATION**

Device Package		Shipping <sup>†</sup>		
MR750	Axial Lead	1000 Units / Box		
MR750G	Axial Lead (Pb-Free)			
MR750RL	Axial Lead			
MR750RLG	Axial Lead (Pb–Free)	800 / Tape & Reel		
MR751	Axial Lead			
MR751G	Axial Lead (Pb-Free)	1000 Units / Box		
MR751RL	Axial Lead			
MR751RLG	Axial Lead (Pb-Free)	800 / Tape & Reel		
MR752	Axial Lead			
MR752G	Axial Lead (Pb-Free)	1000 Units / Box		
MR752RL	Axial Lead	800 / Tape & Reel		
MR752RLG	Axial Lead (Pb–Free)			
MR754	Axial Lead			
MR754G	Axial Lead (Pb-Free)	1000 Units / Box		
MR754RL	Axial Lead			
MR754RLG	Axial Lead (Pb–Free)	800 / Tape & Reel		
MR756	Axial Lead			
MR756G	Axial Lead (Pb-Free)	1000 Units / Box		
MR756RL	Axial Lead			
MR756RLG	Axial Lead (Pb-Free)	800 / Tape & Reel		
MR760	Axial Lead			
MR760G	Axial Lead (Pb–Free)	1000 Units / Box		
MR760RL	Axial Lead	800 / Tape & Reel		
MR760RLG	Axial Lead (Pb-Free)			

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

**AXIAL LEAD BUTTON** CASE 194-04 ISSUE H



NOTES:

CATHODE SYMBOL ON PACKAGE.
 194–01 OBSOLETE, 194–04 NEW STANDARD.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	8.43	8.69	0.332	0.342	
В	5.94	6.25	0.234	0.246	
D	1.27	1.35	0.050	0.053	
ĸ	25.15	25.65	0.990	1.010	

STYLE 1: PIN 1. CATHODE 2. ANODE

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#### PUBLICATION ORDERING INFORMATION

#### LITERATURE FULFILLMENT

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